



Micro Modular System

Die Sorter *m*WW600

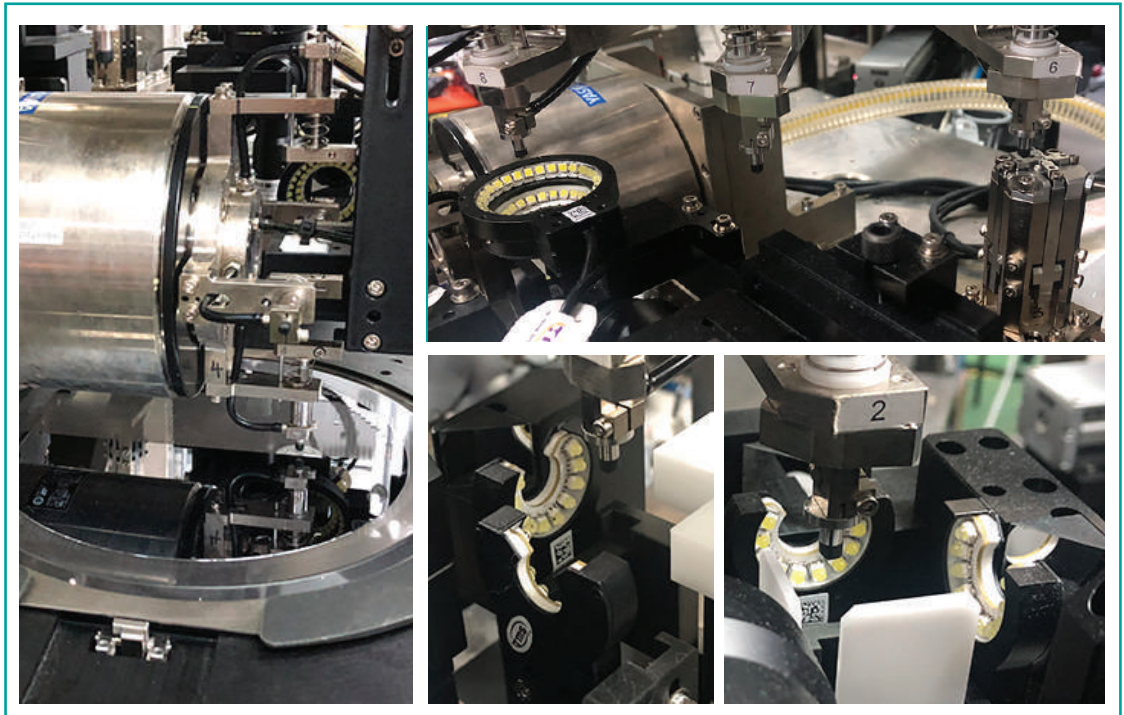
www.mmsis.com

High speed and fully automated vision inspection machine for die sorting. Versatile in its output, supporting 6" and 8" wafer output as well as tape format output.

Designed to be flexible enough to perform 6 sided vision inspections on 6" and 8" wafer, including 12" wafer with a conversion kit, its coverage of commonly used wafer format makes it an ideal inspection solution for the industry.

Features

- Detailed cosmetic inspection with 6S vision inspection (top, bottom, front, back and sides)
- UPH up to 20K
- Placement accuracy +/- 50 micron
- Accurate tracing with high resolution camera up to 10 microns
- Versatile Input: 6", 8" and 12" (with a conversion kit)
- Versatile Output: 6", 8" (with a conversion kit) & Tape & Reel
- Wide range of die size viability
- 4 head wafer input flipper increases throughput
- Automated wafer ring loading and unloading to wafer magazine



Products	Wafer		
Die Size (mm)	Min: 1 x 1	Max: 5 x 5	Aspect Ratio: <2
Die Thickness (mm)	Min: 0.1	Max: 0.8	
Specifications	Input:	Wafer ring (6"/8", 12" with conversion kit)	
	Output:	Tape (width: 8/12/16mm) Wafer ring (8", 6" with conversion kit)	
Vision Inspection	6S (top, bottom, front, back and sides)		
Camera Resolution	5.0MP (Top/ Bottom Vision), 3.2MP (2S Side Vision)		
Minimum Detectable	~10μm		
UPH	Up to 20K (Depending on configuration and die size)		

Footprint	2000mm (W) x 2000mm (L) x 2000mm (H)
Warranty	1 year limited excluding wear and tear parts